What is claimed is:

1. A thermosetting resin sheet containing an inorganic filler, an epoxy resin and a phenolic resin, and being in a B-stage state with a projected area of 17663 mm^2 or more as viewed in a plan view,

wherein

a content of the inorganic filler is 80 wt% or more and 90 wt% or less (excluding 80 wt%), and

an elastic modulus before heat curing is 2.5×10^3 Pa or more and 3×10^4 Pa or less in a temperature range of 90°C to 130°C~~, and~~

~~a content of the inorganic filler is 80 to 90% by weight (excluding 80% by weight)~~.

2. The thermosetting resin sheet according to claim 1, wherein an average particle size of the inorganic filler is 54 μm or less.

3. The thermosetting resin sheet according to claim 1 or 2, containing an elastomer.

4. A thermosetting resin sheet wound body formed by winding a long body of the thermosetting resin sheet according to any one of claims 1 to 3 in a roll form.

5. A method for manufacturing an electronic component package, comprising:

a laminating step of laminating the thermosetting resin sheet according to any one of claims 1 to 3 onto one

or plural electronic components so as to cover the one or plural electronic components; and

a sealed body forming step of forming a sealed body by heat-curing the thermosetting resin sheet,

wherein a ratio of a projected area of the electronic component as viewed in a plan view relative to a projected area of the thermosetting resin sheet as viewed in a plan view is 50% or more.

6. The method for manufacturing an electronic component package according to claim 5, wherein the laminating step is carried out by a thermal pressing process.

7. The method for manufacturing an electronic component package according to claim 5 or 6, further comprising a dicing step of forming an electronic component module by dicing the sealed body.

8. The method for manufacturing an electronic component package according to any one of claims 5 to 7, wherein the electronic component is a semiconductor chip or a semiconductor wafer.